

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Kyung Won Kang	11/12/2004
In Hwan Choi	11/12/2004
RECEIVING PARTY DATA	
Name:	LG Electronics Inc.
Street Address:	20 Yoido-Dong, Youngdungpo-Ku
City:	Seoul 150-010
State/Country:	REPUBLIC OF KOREA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12546490
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ATTORNEY DOCKET NUMBER:	2080-3300C1
NAME OF SUBMITTER:	Richard C. Salfelder
Total Attachments: 2 source=Assignment-2080-3300-C1#page1.tif source=Assignment-2080-3300-C1#page2.tif	

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RECORDATION FORM COVER LETTER PATENTS ONLY

Docket No.: 2080-3300C1

To the Assistant Commissioner for Patents: Please record the attached original documents or copy thereof.

1. Name of conveying party **Kyung Won Kang and In Hwan Choi**

2. Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance:
- Assignment Merger
 - Security Agreement Change of Name
 - Joint Research Agreement
 - Government Interest Assignment
 - Executive Order 9424, Confirmatory License
 - Other _____

Execution Date: **November 12, 2004**

2. Name and address of receiving party(ies):

**LG ELECTRONICS INC.
20, Yoido-dong, Youngdungpo-gu
Seoul, 150-010, Korea**

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s): This document is being filed together with a new application.

A. Patent Application No.(s) **12/546,490**

B. Patent No.(s) **N/A**

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

**JONATHAN Y. KANG, ESQ.
LEE, HONG, DEGERMAN, KANG & WAIMEY
680 South Figueroa Street
Suite 2300
Los Angeles, CA 90017**

6. Total number of applications and patents involved: [**1**]

7. Total fee (37 CFR 3.41) **\$40**

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number: **502290**

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.

Date: **August 24, 2009**

/Richard C. Salfelder/
Richard C. Salfelder, Reg. No. 51,127

OMB No. 0651-0011 (exp. 4/94)

Mail documents to be recorded with required cover sheet information to:

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P.O. Box 1450
Alexandria, VA 22313-1450**

ASSIGNMENT

- (1-8) *Insert Name(s) of Inventor(s)*
- | | |
|--------------------|-----|
| (1) Kyung Won KANG | (5) |
| (2) In Hwan CHOI | (6) |
| (3) | (7) |
| (4) | (8) |

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

- (9) *Insert name of Assignee* (9) LG Electronics Inc.
 (10) *Insert state of Incorporation of Assignee* (10) Korea
 (11) *Insert address of Assignee* (11) 20 Yoido-Dong, Youngdungpo-Ku
 Seoul 150-010, Korea

(hereinafter designated as the Assignee) the entire worldwide right, title and interest in the invention known as

- (12) *Insert identification of Invention, such as Title, Case Number or Foreign Application Number* (12) **DIGITAL E8-VSB RECEPTION SYSTEM AND E8-VSB DATA DEMULTIPLEXING METHOD**

for which the undersigned has (have) executed an application for patent in the United States of America and all patent applications in foreign countries corresponding thereto or based thereon.

- (13) *Insert Date of Signing of Application* (13)

1) The undersigned agree(s) to execute all papers necessary in connection with any original, reissue, divisional and continuing United States and foreign applications for the above-identified invention and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed any agreement in conflict herewith. The undersigned hereby appoints JONATHAN Y. KANG, REG. NO. 38,199; F. JASON FAR-HADIAN, REG. NO. 42,523; AMIT S. SHETH, REG. NO. 50,176; RICHARD C. SALFELDER, REG. NO. 51,127; LEW EDWARD V. MACAPAGAL, REG. NO. 55,416; ROBERT E. KASODY, REG. NO. 50,268

the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: 2004, 12, 12 Signature of Inventor [Signature]
 Date: 2004, 11, 12 Signature of Inventor [Signature]
 Date: _____ Signature of Inventor _____
 Date: _____ Signature of Inventor _____